

SMD High Current Molded Inductors - FCH1350- Series

FCH1350-Series

●Features:

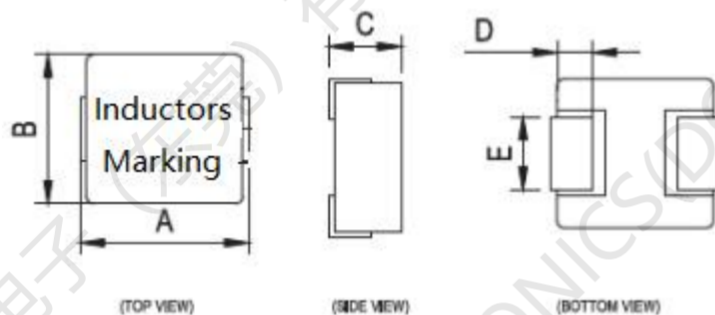
- Ultra low cost
- Shielded constructions
- High current rating up to DC 38Amp
- High current ISATup to DC 60Amp
- Very low DC resistance
- Low Noise
- RoHS compliant

●Applications:

- PDA/Notebook/Desktop/Server applications
- DC/DC converter

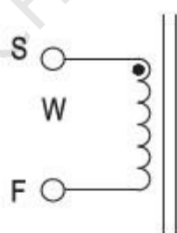


1.Shapes and Dimensions (形状及尺寸)

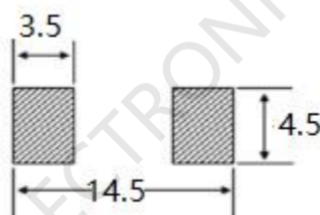


Type	A	B	C	D	E
FCH1350	13.7±0.3	12.8±0.3	5.0 MAX	2.7±0.3	3.8±0.3

2.Schematic:



3.layout recommendation:(mm)



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4. FCH1350 -Series:

Part Number (品名)	Inductance (uH) ±20% (电感值)	DCR(mΩ) (直流阻抗)		Isat DC Current (A) (饱和电流)	Irms DC Current (A) (温升电流)
		Typical	MAX	Typical	Typical
FCH1350-R22M	0.22	0.5	0.7	60.0	38.0
FCH1350-R47M	0.47	1.0	1.5	60.0	36.0
FCH1350-R56M	0.56	1.0	1.5	50.0	35.0
FCH1350-R68M	0.68	1.1	1.6	30.0	30.0
FCH1350-1R0M	1.00	1.8	2.2	28.0	24.0
FCH1350-1R2M	1.20	2.0	3.1	28.0	24.0
FCH1350-1R5M	1.50	1.9	3.2	28.0	24.0
FCH1350-2R2M	2.20	4.0	4.5	25.0	21.0
FCH1350-3R3M	3.30	5.0	7.0	21.0	18.0
FCH1350-3R9M	3.90	7.0	9.0	20.0	16.0
FCH1350-4R7M	4.70	8.9	11.0	21.0	14.0
FCH1350-5R6M	5.60	11.5	13.5	17.0	13.0
FCH1350-6R8M	6.80	13.0	15.0	16.0	12.0
FCH1350-8R2M	8.20	15.0	22.0	14.0	10.0
FCH1350-100M	10.00	16.0	22.0	13.0	9.0
FCH1350-150M	15.00	25.0	30.0	11.0	9.0
FCH1350-220M	22.00	33.0	55.0	8.5	7.0
FCH1350-270M	27.00	50.0	68.0	7.0	6.0
FCH1350-330M	33.00	65.0	84.0	8.0	5.0
FCH1350-470M	47.00	81.0	93.0	5.5	4.5
FCH1350-560M	56.00	102.0	117.0	5.5	4.0

Remark:

<1>Inductance: 100KHz 0.1V

<2>Tolerance of inductance:±20%

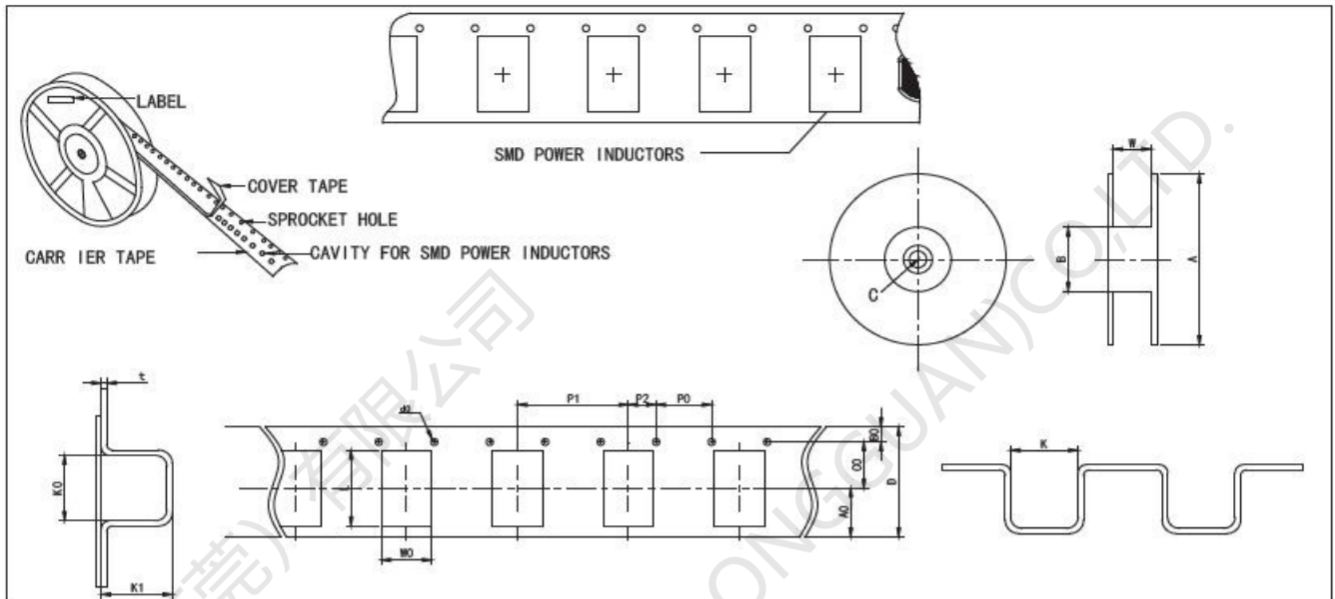
<3>Isat: The value of current indicates that inductance drops 30%(Typical) from its initial value

<4>Irms:The value of current indicates that the temperature of the coil is increase 40°C (Typical)

<5>Test condition: Ta= 25°C

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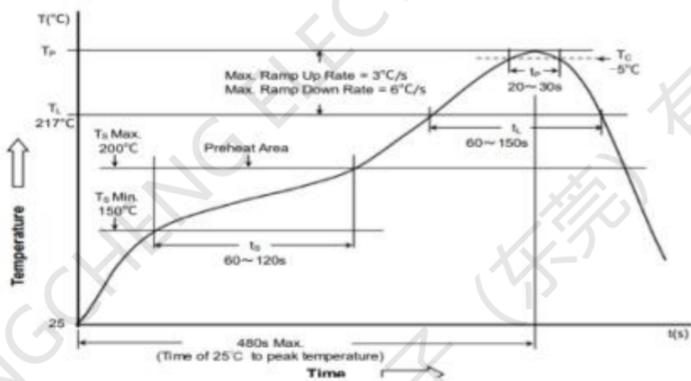
5.FCH1350-Series



●Reel Dimensions & Packing Unit(卷轴尺寸及包装数量)

Part Number 品名	Dimensions of Reel 卷轴尺寸				Packaging Unit 包装数
	A	B	C	W	
FCH1350	330	100.0±2.00	13.5±1.0	24.0±0.50	500pcs/r

6. Reflow Profile for SMT Components



	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm ³	350~2000 mm ³	>2000 mm ³
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.
回流焊参照标准 IPC/JEDEC J-STD-020D.